

SN54S135, SN74S135 QUADRUPLE EXCLUSIVE-OR/NOR GATES

SDLS204

DECEMBER 1972—REVISED MARCH 1988

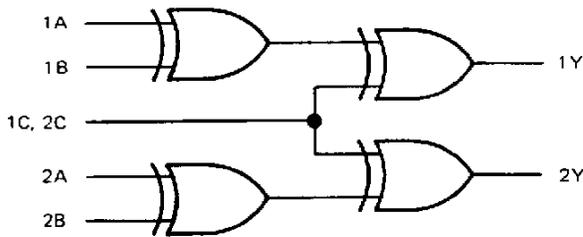
- Fully Compatible with Most TTL and TTL MSI Circuits
- Fully Schottky Clamping Reduces Delay Times . . . 8 ns Typical
- Can Operate as Exclusive-OR Gate (C Input Low) or as Exclusive-NOR Gate (C Input High)

FUNCTION TABLE

INPUTS			OUTPUT
A	B	C	Y
L	L	L	L
L	H	L	H
H	L	L	H
H	H	L	L
L	L	H	H
L	H	H	L
H	L	H	L
H	H	H	H

H = high level, L = low level

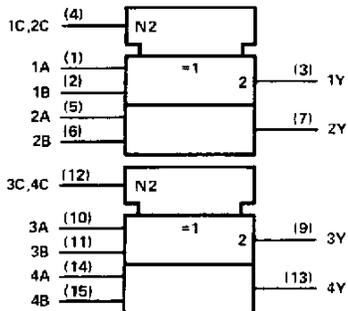
logic diagram (one half)



positive logic

$$Y = A \oplus B \oplus C = \overline{A}\overline{B}C + \overline{A}B\overline{C} + A\overline{B}\overline{C} + ABC$$

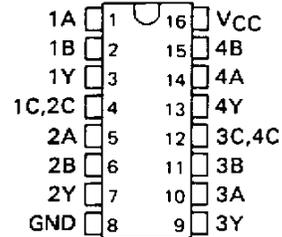
logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers are for D, J, N, and W packages.

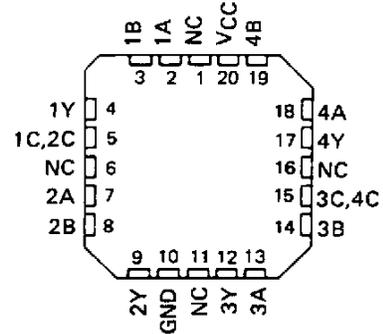
SN54S135 . . . J OR W PACKAGE
SN74S135 . . . D OR N PACKAGE

(TOP VIEW)



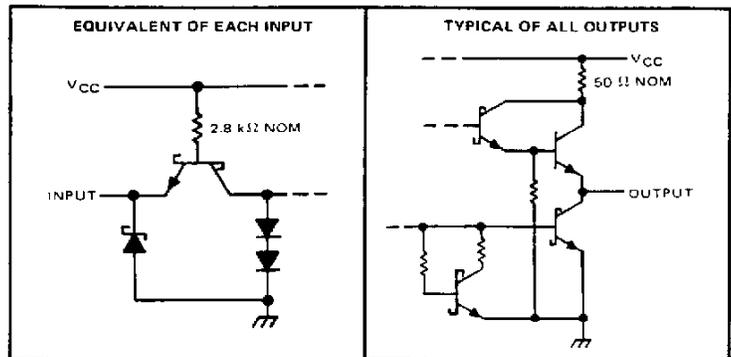
SN54S135 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

schematics of inputs and outputs



Resistor values shown are nominal.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

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SN54S135, SN74S135 QUADRUPLE EXCLUSIVE-OR/NOR GATES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54S135	-55°C to 125°C
SN74S135	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54S135			SN74S135			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-1			-1	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	-65		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V_{IH} High-level input voltage		2			V
V_{IL} Low-level input voltage				0.8	V
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.2	V
V_{OH} High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -1 \text{ mA}$	SN54S' 2.5	3.4		V
		SN74S' 2.7	3.4		
V_{OL} Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 20 \text{ mA}$			0.5	V
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$			1	mA
I_{IH} High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			50	µA
I_{IL} Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.5 \text{ V}$			-2	mA
I_{OS} Short-circuit output current§	$V_{CC} = \text{MAX}$	-40		-100	mA
I_{CC} Supply current	$V_{CC} = \text{MAX}, \text{ See Note 2}$		65	99	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with the inputs grounded and the outputs open.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER	FROM (INPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	B or A = L, C = L	8.5	11	13	ns
t_{PHL}						
t_{PLH}	A or B	B or A = H, C = L	8	9	12	ns
t_{PHL}						
t_{PLH}	A or B	B or A = L, C = H	10	6.5	15	ns
t_{PHL}						
t_{PLH}	A or B	B or A = H, C = H	8.5	7	12	ns
t_{PHL}						
t_{PLH}	C	A = B	8	9.5	12	ns
t_{PHL}						
t_{PLH}	C	A ≠ B	7.5	7.5	11.5	ns
t_{PHL}						

$C_L = 15 \text{ pF}, R_L = 280 \Omega, \text{ See Note 3}$

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN54S135J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN74S135N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S135N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ54S135J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S135J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S135W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S135W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54S135, SN74S135 :

- Catalog: [SN74S135](#)
- Military: [SN54S135](#)

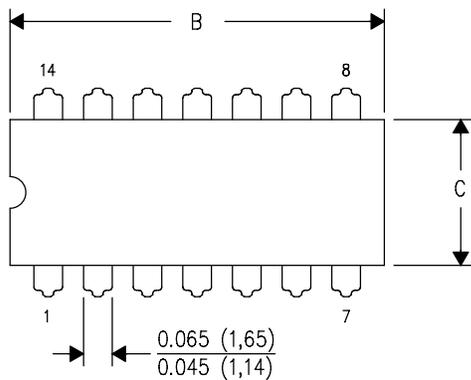
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

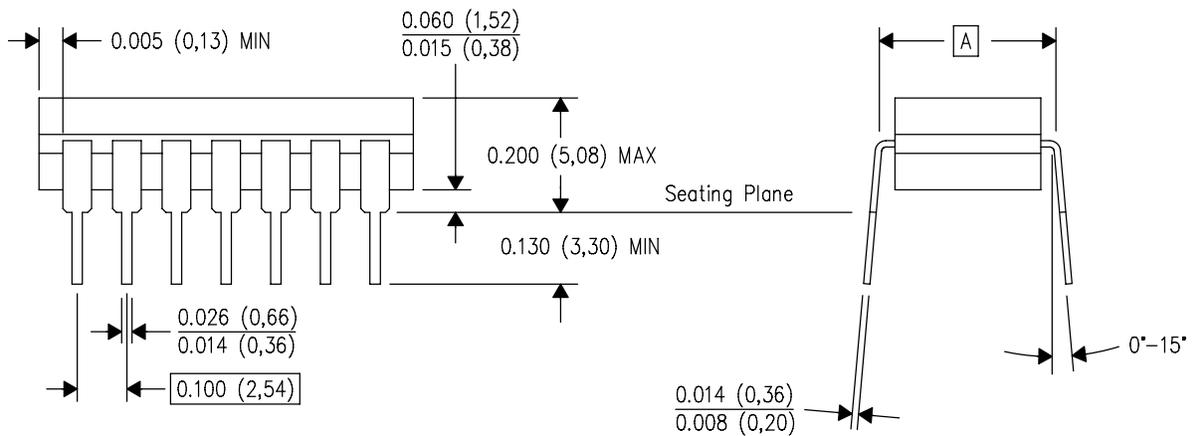
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

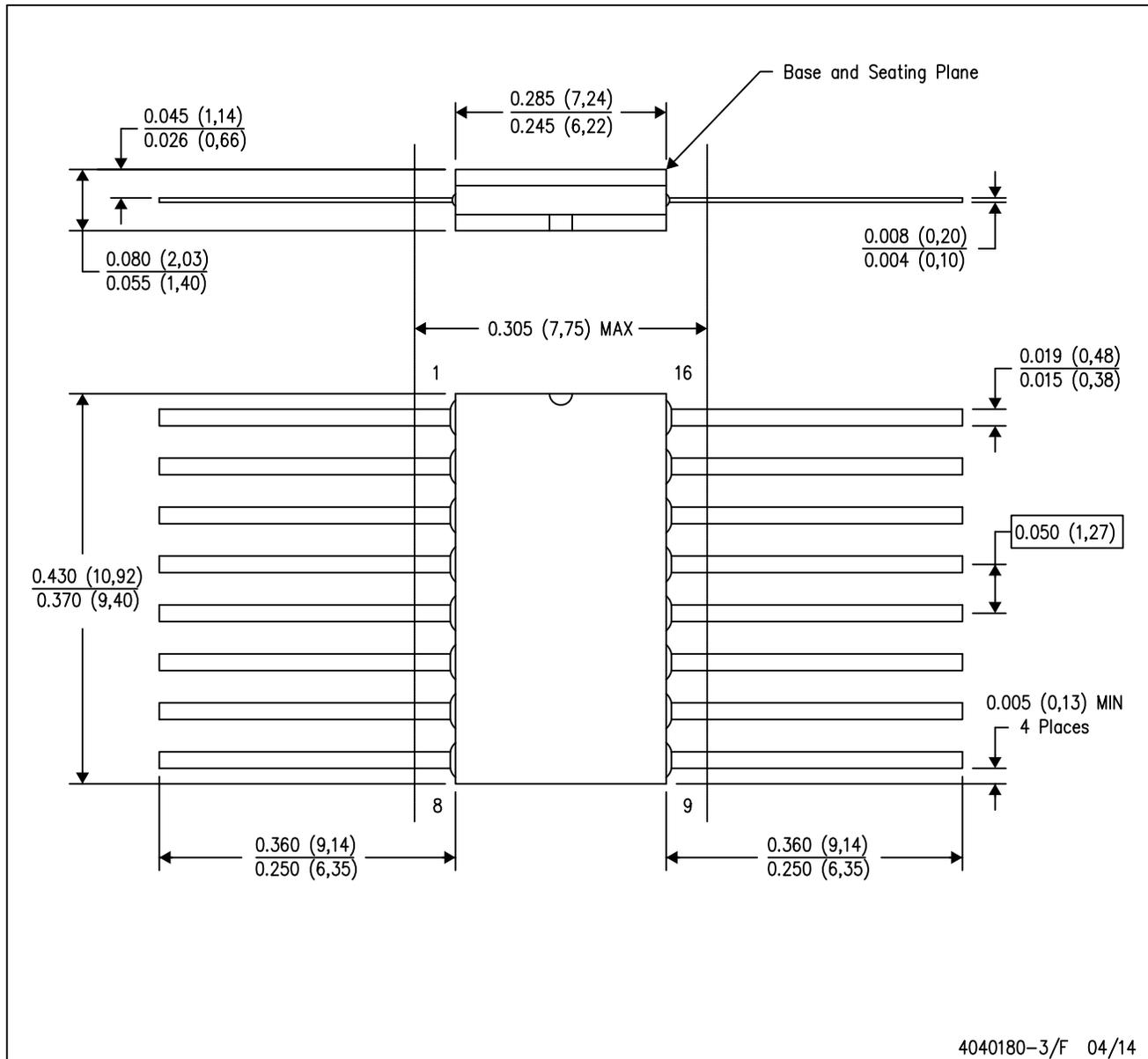


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



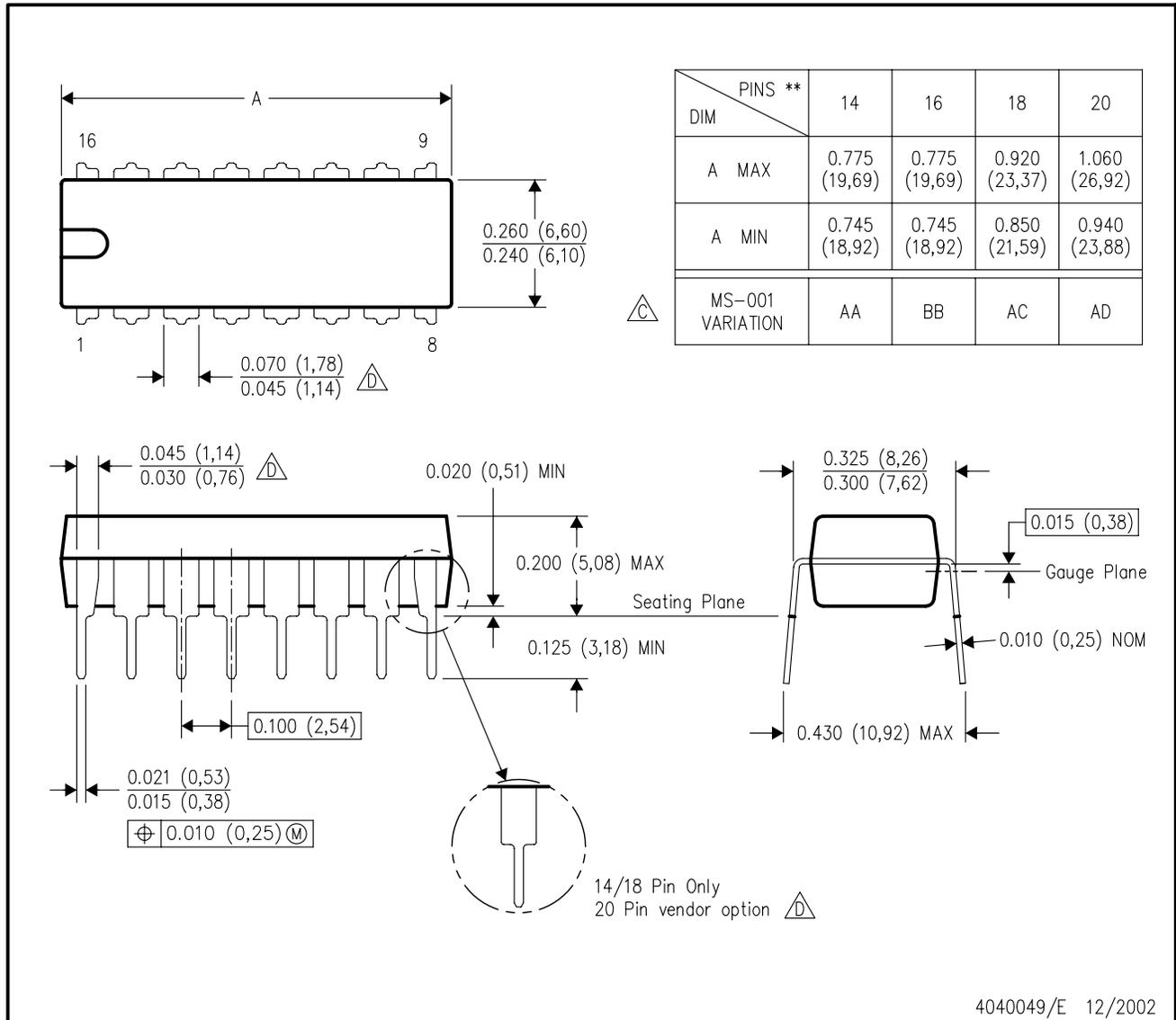
4040180-3/F 04/14

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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